

ABSTRACT

The present invention provides a conductive adhesive that is applicable as means for forming conductive junction to process for surface

5 mounting of electronic parts for vehicle loading and process for the manufacture of the electronic parts per-se for the purpose of substituting soldering therewith. The conductive adhesive according to the present invention is a conductive adhesive produced by dispersing a conductive medium, such as silver powder, in a binder resin component of a one-

10 component epoxy thermosetting resin which has such a composition that the resin comprises, as essential components, an epoxy resin component composed mainly of an epoxy compound with a polycyclic aromatic ring skeleton, and a cyclic acid anhydride as a curing agent component thereof, and is further added with a coupling agent as an adherence imparting agent

15 therefor.